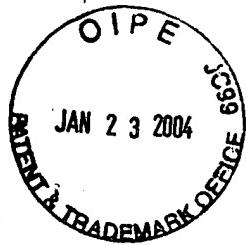


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January 21, 2004

Commissioner For Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Re: Applicant: Wayne Glenn Renken
Title: System and Method for Heating and Cooling Wafer at
Accelerated Rates
Application No.: 10/619,731 Filing Date: July 15, 2003
Examiner: Unknown Group Art Unit: 1725
Docket No.: SENS.007US1 Conf. No.: 7022

Dear Sir:

Transmitted herewith are the following documents in the above-identified application:

- (1) Return Receipt Postcard;
- (2) This Transmittal Letter (in duplicate);
- (3) Voluntary Amendment (3 pages); and
- (4) Power of Attorney by Assignee of Entire Interest (3 pages).

No additional fee is required.

Certificate of Mailing Under 37 CFR 1.8

I hereby certify that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on January 21, 2004.

May S. Brugge
Signature

Respectfully submitted,

Gerald P. Parsons

Gerald P. Parsons
Reg. No. 24,486